

**FL2012M2**
*No Clean Liquid Flux*

**Product Description**

FL2012M2 provides matte solder joints and excellent solderability, with reduction in micro-solderballing and solder bridging at connectors and QFP. The residue left behind is non-tacky, non-corrosive and non-conductive.

**Application**

FL2012M2 is specially formulated for foaming, spraying and dipping processes. On board pre-heat temperature is recommended to be 80 – 100 °C.

**Residue Removal**

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

**Recommended Solvent**

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

**Health and Safety**

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

**Storage**

Under proper storage condition, FL2012M2 can be stored for up to 6 months. FL2012M2 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

**Packaging**

Available in 18kg/carboy.

**Specification**

Item	Result
State	Liquid
Colour	Transparent yellow
Specific Gravity @ 25°C	0.813 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content (110°C, 1hr)	10.0 +/- 0.5 wt%
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	0.08 +/- 0.01 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test	31.0 +/- 2.0 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 1 x 10 <sup>4</sup> Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 <sup>8</sup> Ω, Pass
IPC-TM-650 2.6.3.3	
JIS Z 3197 8.5.3	> 1 x 10 <sup>11</sup> Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "M", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROM1
IPC J-STD-004	
Spread Factor	> 75% (SnCu0.7 & SCS7)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Matte (SCS7)

**DISCLAIMER OF LIABILITY**

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